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|--------------------------|-----------------------------|-------------------------------------|---------------------|
| PCN Number: | 20160118005 | PCN Date: | 2/1/2016 |
| Title: | Datasheet for LDC1000 | | |
| Customer Contact: | PCN Manager | Dept: | Quality Services |
| Change Type: | | | |
| <input type="checkbox"/> | Assembly Site | <input type="checkbox"/> | Design |
| <input type="checkbox"/> | Assembly Process | <input checked="" type="checkbox"/> | Data Sheet |
| <input type="checkbox"/> | Assembly Materials | <input type="checkbox"/> | Part number change |
| <input type="checkbox"/> | Mechanical Specification | <input type="checkbox"/> | Test Site |
| <input type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/> | Test Process |
| | | <input type="checkbox"/> | Wafer Bump Site |
| | | <input type="checkbox"/> | Wafer Bump Material |
| | | <input type="checkbox"/> | Wafer Bump Process |
| | | <input type="checkbox"/> | Wafer Fab Site |
| | | <input type="checkbox"/> | Wafer Fab Materials |
| | | <input type="checkbox"/> | Wafer Fab Process |

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification etc.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



LDC1000

SNOSCX2C – SEPTEMBER 2013 – REVISED SEPTEMBER 2015

Changes from Revision B (March 2015) to Revision C

Page

| | |
|---|----|
| • Changed XOUT pin description to clarify proper crystal connection..... | 4 |
| • Added instructions on proper DAP connection..... | 4 |
| • Added conditions for L measurement resolution..... | 6 |
| • Changed TYP to NOM..... | 7 |
| • Changed Some descriptions of device functionality for better clarity and consistency | 9 |
| • Changed RP Conversion equation for clarity | 12 |
| • Added extended SPI transaction figure for clarity | 17 |
| • Changed Register maps to include Clock Configuration and Threshold Registers | 18 |
| • Changed description of Min Sensor frequency for clarity | 21 |
| • Added documentation of registers 0x05, 0x06, and 0x08 | 21 |
| • Changed description of OSC Status to include possible causes. | 23 |
| • Changed some details on Application Information for improved clarity and consistency. | 24 |
| • Deleted lateral and rotation images from example applications, as example application details axial sensing configuration | 25 |
| • Changed details of example design for improved clarity..... | 26 |

The datasheet number will be changing.

| | | |
|---------------|--------------|-----------------|
| Device Family | Change From: | Change To: |
| LDC1000 | SNOSCX2B | SNOSCX2C |

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/LDC1000>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

| | | | |
|---|-------------|-------------|--|
| Changes to product identification resulting from this PCN: | | | |
| None. | | | |
| Product Affected: | | | |
| LDC1000NHRJ | LDC1000NHRR | LDC1000NHRT | |

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|-----------------|--|
| USA | PCNAmericasContact@list.ti.com |
| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| Japan | PCNJapanContact@list.ti.com |